Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm PCBA, IO Board, RAM, HDD, TOUCHPAD</td>
<td>5</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Li-ion polymer Battery, lithium coin batteries</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Adapter Cable, Power Core</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
</tbody>
</table>
Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Base Rubber and Dis-fasten Screws *8

2. Remove Keyboard and Pull out The KB’s FFC Cable.
3. Dis-fasten TOP Screw*6

4. Dis-fasten the Base Screws*8 and Open Base Case with Top Cover
5. Remove The Battery’s Black Tape and Dis-fasten Battery’s Screws *2

6. Remove the Battery
7. Dis-fasten the HDD's Screws *4, Pull Out HDD’s FPC Cable and Remove HDD.

8. Dis-fasten The HDD Bracket Screw*4
9. Remove the HDD Bracket

10. Remove the HDD Rubber and FPC Cable
11. Remove the DDR's Acetate Tape and the HDD

12. Remove the Wlan Card's Acetate Tape and Dis-fasten the Wlan Card's Screw *1
13. Pull Out the WLan Cable and Remove the WLan Card

14. Separate WLan Cable
15. Dis-Fasten the Thermal Model's Screws*3

16. Remove the Thermal Model.
17. Dis-fasten the LVDS Cable’s Screws*1 and Pull out the LVDS Cable.

18. Pull out the MIC cable
19. Remove the DC-in Sponge.

20. Pull out the DC-in cable, Dis-fasten the DC-in Screws*1 and Remove the Dc-in Cable
21. Pull out the Speaker Cable

22. Dis-fasten the Speaker's Screws
23. Remove the Speaker Cable

24. Pull out the IO Board FFC*2 and Touch Pad FFC*1.
25. Dis-fasten the MotherBoard Screws*2 and the IO Board Screws*1

26. Remove the MotherBoard and the IO Board.
27. Remove the IO Board FFC Cable* 2

28. Remove the DDR Mylar on the MotherBoard.
29. Remove the Touch Pad FFC on the MotherBoard

30. Remove the Acetate Tape and the MB's Al Foil
31. Remove the CMOS Battery

32. Dis-fasten the LCD Hinge-R screws*1
33. Remove Hinge Cover

34. Dis-fasten LCD Hinge screw*2
35. Separate LCD Module with Base units

36. Dis-fasten the Palmrest screw *6
37. Remove the Palmrest

38. Remove LCD Rubber and Dis-fasten the Screw*8
39. Remove the LCD Back Cover.

40. Dis-fasten the LCD Hinge Screw*4 and Remove the Hinge
41. Dis the CCD Hinge Screw*2

42. Pull out the LVDS Cable and Remove the CCD Model.
43. Remove the LCD Hinge Al Foil*2 and the CCD Hinge Al Foil*1

44. Remove the W Lan Main Cable and W Lan Aux Cable
45. Dis-fasten the LCM Screw*4

46. Remove the LCM Part
47. Dis-fasten the LCD Bracket Screw*4

48. Separate the LCM and the LCD Bracket.
49. Take off the CCD Liens*2

50. Dis-fasten the CCD Screw*2 and Separation the CCD Part
51. Remove the CCD Hinge

52. Remove the MIC Cable and CCD Model.
53. Remove the CCD Lens*1

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).